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ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises: a semiconductor substrate having a first region and a second region; a plurality of first sub-external terminals disposed on the first region; a plurality of second sub-external terminals composed of terminals to be grounded and terminals to be connected to a power source; a plurality of second external terminals disposed on the second region; a first sub-wiring structure provided on the first region for electrically connecting the plurality of first sub-external terminals and a plurality of circuit element connecting pads; a second sub-wiring structure for electrically connecting the plurality of second sub-external terminals and the plurality of circuit element connecting pads; and a plurality of second wiring structures provided from the first region to the second region for electrically connecting the plurality of second external terminals and the plurality of circuit element connecting pads.